

250mW, High Speed Switching Array

FEATURES

- Fast switching speed
- High reverse breakdown voltage rating
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant

APPLICATIONS

- For general purpose switching application

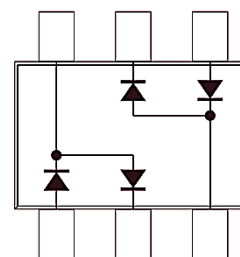
MECHANICAL DATA

- Case: SOT-363
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Weight: 8.00mg (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
P_D	250	mW
V_{RRM}	85	V
I_F	200	mA
V_F at $I_F = 150\text{mA}$	1.25	V
$T_{J\text{MAX}}$	150	°C
Package	SOT-363	
Configuration	Array	



SOT-363



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Marking code on the device		K1	
Power dissipation	P_D	250	mW
Repetitive peak reverse voltage	V_{RRM}	85	V
Repetitive peak forward current	I_{FRM}	450	mA
Mean Forward current	I_F	200	mA
Non-Repetitive peak forward surge current	$t = 1 \mu\text{s}$	4.5	A
	$t = 1 \text{ s}$	0.5	A
Junction temperature range	T_J	-55 to +150	°C
Storage temperature range	T_{STG}	-55 to +150	°C

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	MIN	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 1\text{mA}$	V_F	-	0.715	V
	$I_F = 10\text{mA}$		-	0.855	V
	$I_F = 50\text{mA}$		-	1.000	V
	$I_F = 100\text{mA}$		-	1.200	V
	$I_F = 150\text{mA}$		-	1.250	V
Reverse voltage	$I_R = 2.5\mu\text{A}$	V_R	75	-	V
Reverse current @ rated V_R per diode	$V_R = 75\text{V}$	I_R	-	1	μA
Junction capacitance	1MHz, $V_R = 0\text{V}$	C_J	-	1.5	pF
Reverse recovery time	$I_F = I_R = 10\text{mA}$, $R_L = 100\Omega$	t_{rr}	-	4	ns

Notes:

1. Pulse test with PW = 0.3ms

ORDERING INFORMATION		
ORDERING CODE⁽¹⁾	PACKAGE	PACKING
BAV99S RFG	SOT-363	3K / 7" Reel
BAV99S RF	SOT-363	3K / 7" Reel

Notes:

1. "G" means green compound (halogen-free)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 Maximum Permissible Continuous Forward Current As A Function of Soldering Point Temperature

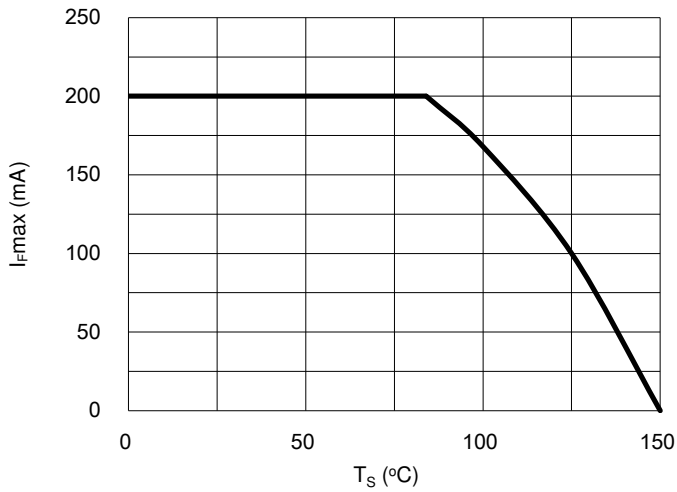


Fig. 2 Forward Current As A Function of Forward Voltage

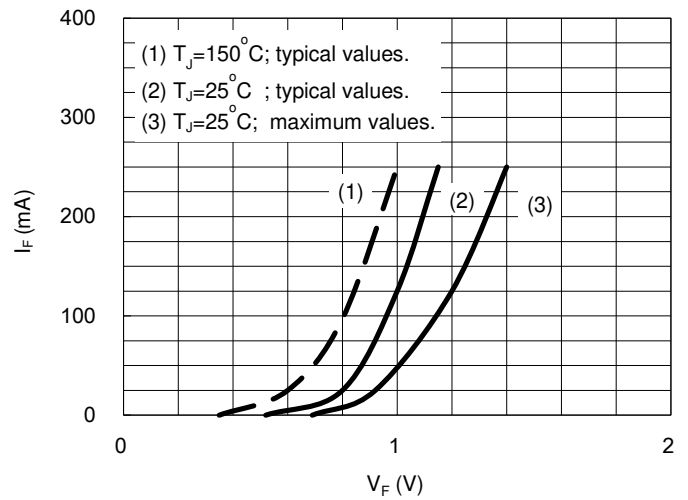
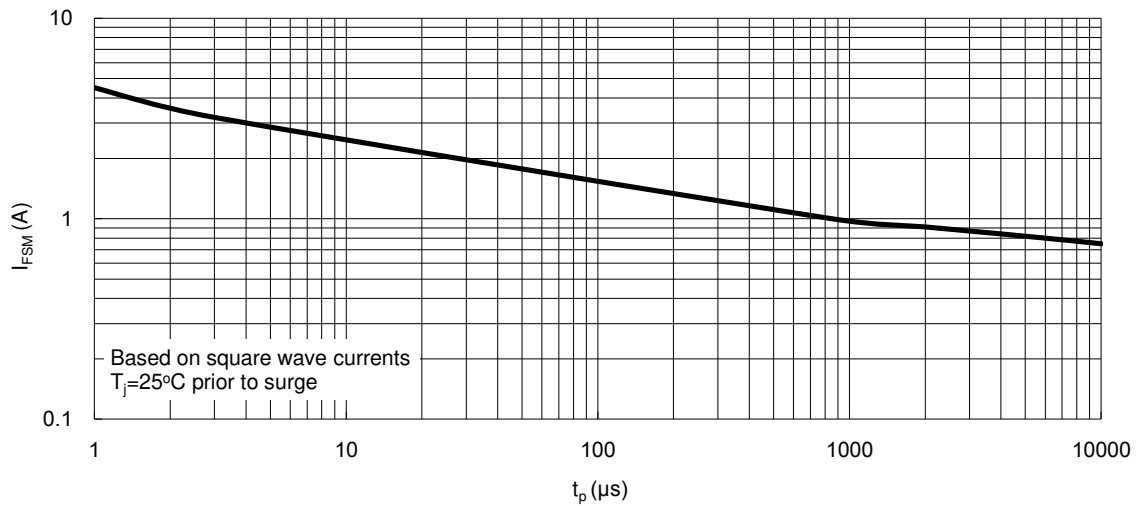
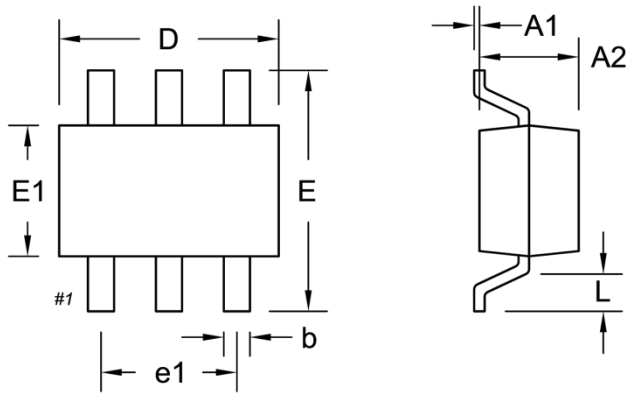


Fig. 3 Maximum Permissible Non-Repetitive Peak Forward Current As A Function of Pulse Duration



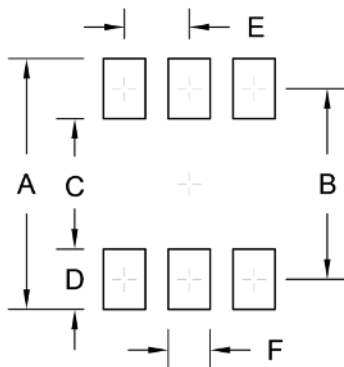
PACKAGE OUTLINE DIMENSION

SOT-363



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A1	0.00	0.10	0.000	0.004
A2	0.85	1.05	0.033	0.041
b	0.15	0.35	0.006	0.014
D	2.00	2.20	0.079	0.087
E	2.15	2.45	0.085	0.096
E1	1.15	1.35	0.045	0.053
e1	1.20	1.40	0.047	0.055
L	0.25	0.46	0.010	0.018

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.50	0.098
B	1.90	0.075
C	1.30	0.051
D	0.60	0.024
E	0.65	0.026
F	0.42	0.017

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